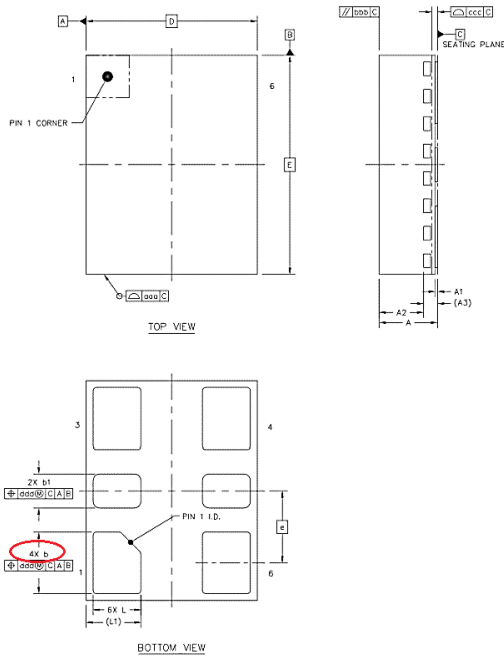


Process & Product Change Notice: 0500002

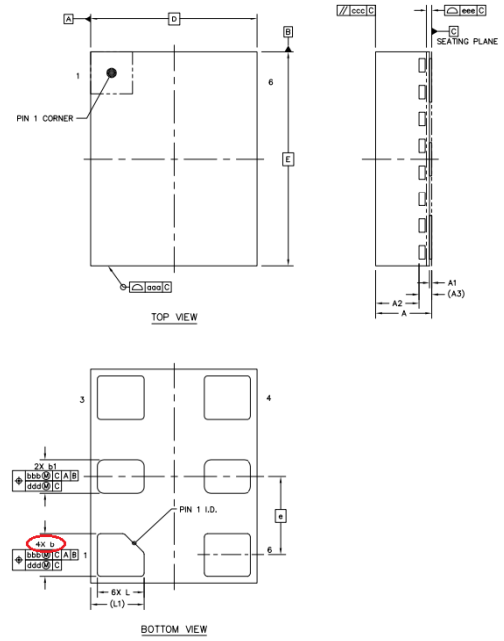
PCN Doc:	PCN-0500002	PCN#:	0500002		
PCN Date:	2022/7/22	Effective Date:	2022/7/31		
Title:	AS500x 6-pin 3.2x2.5mm package outline adjustment				
Originator:	Foeking Wu	Mail:	foeking.wu@aeonsemi.com	Dept:	Marketing
Customer contact:	Aeonsemi Marketing	Mail:	marketing@aeonsemi.com	Dept:	Marketing
PCN Type:					
<input type="checkbox"/> Datasheet <input type="checkbox"/> Foundry <input type="checkbox"/> Packing <input type="checkbox"/> Product Revision <input checked="" type="checkbox"/> Assembly <input type="checkbox"/> Labeling <input type="checkbox"/> Discontinuance <input type="checkbox"/> Test <input type="checkbox"/> Other					
Last Order Date of Unchanged Product: 2022/12/31					
PCN Details					
Description of Change:					
<p>The AS500x 6-pin 3225 package devices are assembled in a new package design where the length of side pins is reduced from 0.9mm to 0.65mm.</p> <p>The new package is fully compatible with the PCB land pattern of old design, thus there's no requirement on PCB changes. See Appendix A for details.</p> <p>The changes will take effect on 2022/7/22 from datasheet version 1.10.</p>					
Reason for Change:					
New package outline design improves the PCB solderability of the device by increasing pad spacing.					
Impact on Form, Fit, Function, Quality, Reliability:					
<p>There is no change to fit, function, quality, or reliability of these devices.</p> <p>The change to form is limited to slightly larger pad spacing comparing with the origin one.</p> <p>Electrical parameters and ordering part number remain unchanged.</p>					
Affected Manufacture Site:					
Assembly house: ASE(CL) Taiwan.					
Product Identification:					
AS5001, AS5002, AS5003.					
Qualification Samples:					
Available upon request.					
Qualification Plan Summary					
See Appendix B.					

Appendix A – Package design update

Package design of unchanged product



New package design



Symbol	Min	Nom	Max	Symbol	Min	Nom	Max
b	0.85 mm	0.9 mm	0.95 mm	b	0.6 mm	0.65 mm	0.7 mm

Appendix B --- Qualification Report					
Type	Test Item (Standards)	Condition	Sample Size	Electrical Test Readouts	Result (1Accept/2Reject)
	ATE test	Standard ATE test at Room Temp	300 pcs	Pre-ATE testing	All Pass
	SAT	C-SAM	300 pcs	Pre-SAT image	All Pass
	Pre-Waveform check	Bench power up test	300 pcs	Device waveform output	All Pass
Pre-Conditioning Lead-Free MSL1 (JESD22-A113)	TCT	Ta= -40°C to +125°C	300 pcs	5 Cycles	All Pass
	Bake	Temp = 125°C 24 Hours	300 pcs	24 hrs	All Pass
	Soak	Temp = 85°C, 85%RH, 168 hours	300 pcs	168 hrs	All Pass
	Reflow	standard	300 pcs	3 Cycles	All Pass
	Post-Waveform check	Bench power up test	300 pcs	Device waveform output	All Pass
	SAT	C-SAM	300 pcs	Post-SAT image	All Pass
	ATE test	Standard ATE test at Room Temp	300 pcs	Post- ATE testing	All Pass